

AMENDMENTS TO THE CLAIMS

1-156. (Canceled)

157 (New). A semiconductor light-emitting device constituted by mounting a semiconductor light-emitting element on a base substance, wherein

the semiconductor light-emitting element has outgoing light having an emission wavelength of 390 to 420 nm; and

there is included a fluorescent substance that is excited by outgoing light from the semiconductor light-emitting element and emits red light having an emission wavelength with its main emission peak in a wavelength range of 600 to 670 nm, wherein

the fluorescent substance is composed of any one or more selected from a fluorescent substance group consisting of:

$M_2 O_2 S : Eu$ (M is any one or more elements selected from La, Gd and Y);

$0.5 MgF_2 \cdot 3.5MgO \cdot GeO_2 : Mn$;

$Y_2 O_3 : Eu$;

$Y(P, V) O_4 : Eu$; and

$YVO_4 : Eu$.

158 (New). A semiconductor light-emitting device constituted by mounting a semiconductor light-emitting element on a base substance, wherein

the semiconductor light-emitting element has outgoing light having an emission wavelength in a range of 390 to 420 nm; and

there is included a fluorescent substance that is excited by outgoing light from the semiconductor light-emitting element and emits green light having an emission wavelength with its main emission peak in a wavelength range of 500 to 540 nm, wherein

the fluorescent substance is composed of any one or more selected from a fluorescent substance group consisting of:

$\text{RMg}_2\text{Al}_{1.6}\text{O}_{2.7}$: Eu, Mn (R is any one or both elements selected from Sr and Ba);

$\text{RMgAl}_{1.0}\text{O}_{1.7}$: Eu, Mn (R is any one or both elements selected from Sr and Ba);

ZnS : Cu;

SrAl_2O_4 : Eu;

SrAl_2O_4 : Eu, Dy;

ZnO : Zn;

$\text{Zn}_2\text{Ge}_2\text{O}_4$: Mn;

Zn_2SiO_4 : Mn; and

$\text{Q}_3\text{MgSi}_2\text{O}_8$: Eu, Mn (Q is any one or more elements selected from Sr, Ba and Ca).

159 (New). A semiconductor light-emitting device constituted by mounting a semiconductor light-emitting element on a base substance, wherein

the semiconductor light-emitting element has outgoing light having an emission wavelength in a range of 390 to 420 nm; and

there is included a fluorescent substance that is excited by outgoing light from the semiconductor light-emitting element and emits blue light having an emission wavelength with its main emission peak in a wavelength range of 410 to 480 nm, wherein

the fluorescent substance is composed of any one or more selected from a fluorescent substance group consisting of:

$\text{Al}_{1.0}(\text{PO}_4)_6\text{Cl}_2 : \text{Eu}$ (A is any one or more elements selected from Sr, Ca, Ba, Mg and Ce);

$\text{XMg}_2\text{Al}_{1.6}\text{O}_{2.7} : \text{Eu}$ (X is any one or both elements selected from Sr and Ba);

$\text{XMgAl}_{1.0}\text{O}_{1.7} : \text{Eu}$ (X is any one or both elements selected from Sr and Ba);

$\text{ZnS} : \text{Ag}$;

$\text{Sr}_{1.0}(\text{PO}_4)_6\text{Cl}_2 : \text{Eu}$;

$\text{Ca}_{1.0}(\text{PO}_4)_6\text{F}_2 : \text{Sb}$;

$\text{Z}_3\text{MgSi}_2\text{O}_8 : \text{Eu}$ (Z is any one or more elements selected from Sr, Ca and Ba);

$\text{SrMgSi}_2\text{O}_8 : \text{Eu}$;

$\text{Sr}_2\text{P}_2\text{O}_7 : \text{Eu}$; and

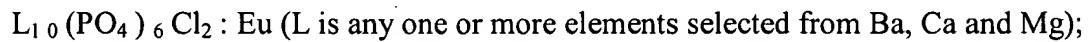
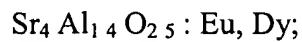
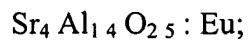
$\text{CaAl}_2\text{O}_4 : \text{Eu, Nd}$.

160 (New). A semiconductor light-emitting device constituted by mounting a semiconductor light-emitting element on a base substance, wherein

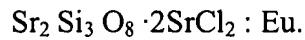
the semiconductor light-emitting element has outgoing light having an emission wavelength in a range of 390 to 420 nm; and

there is included a fluorescent substance that is excited by outgoing light from the semiconductor light-emitting element and emits blue green light having an emission wavelength with its main emission peak in a wavelength range of 480 to 500 nm, wherein

the fluorescent substance is composed of any one or more selected from a fluorescent substance group consisting of:



and



161 (New). A semiconductor light-emitting device constituted by mounting a semiconductor light-emitting element on a base substance, wherein

the semiconductor light-emitting element has outgoing light having an emission wavelength in a range of 390 to 420 nm; and

there is included a fluorescent substance that is excited by outgoing light from the semiconductor light-emitting element and emits orange light having an emission wavelength with its main emission peak in a wavelength range of 570 to 600 nm.

162 (New). The semiconductor light-emitting device according to Claim 161, wherein the fluorescent substance is composed of any one or more selected from a fluorescent substance group consisting of:



ZnS: Cu, Mn, Co.

163 (New). The semiconductor light-emitting device according to Claim 157, wherein
a sealing resin for sealing at least a part of the base substance and the semiconductor
light-emitting element is included; and

the sealing resin contains the fluorescent substance.

164 (New). The semiconductor light-emitting device according to Claim 158, wherein
a sealing resin for sealing at least a part of the base substance and the semiconductor
light-emitting element is included; and

the sealing resin contains the fluorescent substance.

165 (New). The semiconductor light-emitting device according to Claim 159, wherein
a sealing resin for sealing at least a part of the base substance and the semiconductor
light-emitting element is included; and

the sealing resin contains the fluorescent substance.

166 (New). The semiconductor light-emitting device according to Claim 160, wherein
a sealing resin for sealing at least a part of the base substance and the semiconductor
light-emitting element is included; and

the sealing resin contains the fluorescent substance.

167 (New). The semiconductor light-emitting device according to Claim 161, wherein

a sealing resin for sealing at least a part of the base substance and the semiconductor light-emitting element is included; and

the sealing resin contains the fluorescent substance.

168 (New). The semiconductor light-emitting device according to Claim 163, wherein

the base substance is a lead frame having a cup-shaped mount section;

the semiconductor light-emitting element is disposed at the bottom of the cup-shaped mount section of the lead frame and electrically connected to another lead frame by wire bonding; and

at least a part of the two lead frames and the semiconductor light-emitting element are sealed with the sealing resin.

169 (New). The semiconductor light-emitting device according to Claim 163, wherein

the base substance is an insulator connected to ends of a pair of lead frames;

the semiconductor light-emitting element is connected to metallic wiring formed on the insulator; and

at least a part of the pair of lead frames, the insulator and the semiconductor light-emitting element are sealed with the sealing resin.

170 (New). The semiconductor light-emitting device according to Claim 157, wherein

the base substance is a lead frame having a cup-shaped mount section;

the semiconductor light-emitting element is disposed at the bottom of the cup-shaped mount section of the lead frame and electrically connected to another lead frame by wire bonding;

the fluorescent substance is filled in the cup-shaped mount section; and

at least a part of the two lead frames, the semiconductor light-emitting element and the fluorescent substance are sealed with a sealing resin.

171 (New). The semiconductor light-emitting device according to Claim 158, wherein

the base substance is a lead frame having a cup-shaped mount section;

the semiconductor light-emitting element is disposed at the bottom of the cup-shaped mount section of the lead frame and electrically connected to another lead frame by wire bonding;

the fluorescent substance is filled in the cup-shaped mount section; and

at least a part of the two lead frames, the semiconductor light-emitting element and the fluorescent substance are sealed with a sealing resin.

172. (Currently amended) The semiconductor light-emitting device according to Claim 159, wherein

the base substance is a lead frame having a cup-shaped mount section;

the semiconductor light-emitting element is disposed at the bottom of the cup-shaped mount section of the lead frame and electrically connected to another lead frame by wire bonding;

the fluorescent substance is filled in the cup-shaped mount section; and

at least a part of the two lead frames, the semiconductor light-emitting element and the fluorescent substance are sealed with a sealing resin.

173 (New). The semiconductor light-emitting device according to Claim 160, wherein

the base substance is a lead frame having a cup-shaped mount section;

the semiconductor light-emitting element is disposed at the bottom of the cup-shaped mount section of the lead frame and electrically connected to another lead frame by wire bonding;

the fluorescent substance is filled in the cup-shaped mount section; and

at least a part of the two lead frames, the semiconductor light-emitting element and the fluorescent substance are sealed with a sealing resin.

174 (New). The semiconductor light-emitting device according to Claim 161, wherein

the base substance is a lead frame having a cup-shaped mount section;

the semiconductor light-emitting element is disposed at the bottom of the cup-shaped mount section of the lead frame and electrically connected to another lead frame by wire bonding;

the fluorescent substance is filled in the cup-shaped mount section; and

at least a part of the two lead frames, the semiconductor light-emitting element and the fluorescent substance are sealed with a sealing resin.

175 (New). The semiconductor light-emitting device according to Claim 157, wherein

the base substance is a lead frame having a cup-shaped mount section;

the semiconductor light-emitting element is disposed at the bottom of the cup-shaped mount section of the lead frame and electrically connected to another lead frame by wire bonding;

a coating member is filled in the cup-shaped mount section and the fluorescent substance is disposed on the coating member; and

at least a part of the two lead frames, the semiconductor light-emitting element, the coating member and the fluorescent substance are sealed with a sealing resin.

176 (New). The semiconductor light-emitting device according to Claim 158, wherein

the base substance is a lead frame having a cup-shaped mount section;

the semiconductor light-emitting element is disposed at the bottom of the cup-shaped mount section of the lead frame and electrically connected to another lead frame by wire bonding;

a coating member is filled in the cup-shaped mount section and the fluorescent substance is disposed on the coating member; and

at least a part of the two lead frames, the semiconductor light-emitting element, the coating member and the fluorescent substance are sealed with a sealing resin.

177 (New). The semiconductor light-emitting device according to Claim 159, wherein

the base substance is a lead frame having a cup-shaped mount section;

the semiconductor light-emitting element is disposed at the bottom of the cup-shaped mount section of the lead frame and electrically connected to another lead frame by wire bonding;

a coating member is filled in the cup-shaped mount section and the fluorescent substance is disposed on the coating member; and

at least a part of the two lead frames, the semiconductor light-emitting element, the coating member and the fluorescent substance are sealed with a sealing resin.

178 (New). The semiconductor light-emitting device according to Claim 160, wherein

the base substance is a lead frame having a cup-shaped mount section;

the semiconductor light-emitting element is disposed at the bottom of the cup-shaped mount section of the lead frame and electrically connected to another lead frame by wire bonding;

a coating member is filled in the cup-shaped mount section and the fluorescent substance is disposed on the coating member; and

at least a part of the two lead frames, the semiconductor light-emitting element, the coating member and the fluorescent substance are sealed with a sealing resin.

179 (New). The semiconductor light-emitting device according to Claim 161, wherein

the base substance is a lead frame having a cup-shaped mount section;

the semiconductor light-emitting element is disposed at the bottom of the cup-shaped mount section of the lead frame and electrically connected to another lead frame by wire bonding;

a coating member is filled in the cup-shaped mount section and the fluorescent substance is disposed on the coating member; and

at least a part of the two lead frames, the semiconductor light-emitting element, the coating member and the fluorescent substance are sealed with a sealing resin.

180 (New). The semiconductor light-emitting device according to Claim 157, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected the metallic wiring on the substrate;

a sealing resin for sealing the semiconductor light-emitting element is included; and

the sealing resin contains the fluorescent substance.

181 (New). The semiconductor light-emitting device according to Claim 158, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected the metallic wiring on the substrate;

a sealing resin for sealing the semiconductor light-emitting element is included; and

the sealing resin contains the fluorescent substance.

182 (New). The semiconductor light-emitting device according to Claim 159, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected the metallic wiring on the substrate;

a sealing resin for sealing the semiconductor light-emitting element is included; and

the sealing resin contains the fluorescent substance.

183 (New). The semiconductor light-emitting device according to Claim 160, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected the metallic wiring on the substrate;

a sealing resin for sealing the semiconductor light-emitting element is included; and

the sealing resin contains the fluorescent substance.

184 (New). The semiconductor light-emitting device according to Claim 161, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a sealing resin for sealing the semiconductor light-emitting element is included; and

the sealing resin contains the fluorescent substance.

185 (New). The semiconductor light-emitting device according to Claim 157, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate and disposed in a recessed portion; and

the fluorescent substance is filled in the recessed portion.

186 (New). The semiconductor light-emitting device according to Claim 158, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate and disposed in a recessed portion; and

the fluorescent substance is filled in the recessed portion.

187 (New). The semiconductor light-emitting device according to Claim 159, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate and disposed in a recessed portion; and

the fluorescent substance is filled in the recessed portion.

188 (New). The semiconductor light-emitting device according to Claim 160, wherein
the base substance is a substrate provided with metallic wiring;
the semiconductor light-emitting element is electrically connected to the metallic
wiring on the substrate and disposed in a recessed portion; and
the fluorescent substance is filled in the recessed portion.

189 (New). The semiconductor light-emitting device according to Claim 161, wherein
the base substance is a substrate provided with metallic wiring;
the semiconductor light-emitting element is electrically connected to the metallic
wiring on the substrate and disposed in a recessed portion; and
the fluorescent substance is filled in the recessed portion.

190 (New). The semiconductor light-emitting device according to Claim 185, wherein
the recessed portion is formed by a frame disposed on the substrate.

191 (New). The semiconductor light-emitting device according to Claim 157, wherein
the base substance is a substrate provided with metallic wiring;
the semiconductor light-emitting element is electrically connected to the metallic
wiring on the substrate and disposed in a recessed portion;
a sealing resin is filled in the recessed portion; and
the fluorescent substance is disposed on the sealing resin.

192 (New). The semiconductor light-emitting device according to Claim 158, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate and disposed in a recessed portion;

a sealing resin is filled in the recessed portion; and

the fluorescent substance is disposed on the sealing resin.

193 (New). The semiconductor light-emitting device according to Claim 159, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate and disposed in a recessed portion;

a sealing resin is filled in the recessed portion; and

the fluorescent substance is disposed on the sealing resin.

194 (New). The semiconductor light-emitting device according to Claim 160, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate and disposed in a recessed portion;

a sealing resin is filled in the recessed portion; and

the fluorescent substance is disposed on the sealing resin.

195 (New). The semiconductor light-emitting device according to Claim 161, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate and disposed in a recessed portion;

a sealing resin is filled in the recessed portion; and

the fluorescent substance is disposed on the sealing resin.

196 (New). The semiconductor light-emitting device according to Claim 157, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

the fluorescent substance is contained in the sealing resin.

197 (New). The semiconductor light-emitting device according to Claim 158, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

the fluorescent substance is contained in the sealing resin.

198 (New). The semiconductor light-emitting device according to Claim 159, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

the fluorescent substance is contained in the sealing resin.

199 (New). The semiconductor light-emitting device according to Claim 160, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

the fluorescent substance is contained in the sealing resin.

200 (New). The semiconductor light-emitting device according to Claim 161, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

the fluorescent substance is contained in the sealing resin.

201 (New). The semiconductor light-emitting device according to Claim 157, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a shielding body for shielding light directly emitted from the semiconductor light-emitting element to the outside of the semiconductor light-emitting device is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

202 (New). The semiconductor light-emitting device according to Claim 158, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a shielding body for shielding light directly emitted from the semiconductor light-emitting element to the outside of the semiconductor light-emitting device is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

203 (New). The semiconductor light-emitting device according to Claim 159, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a shielding body for shielding light directly emitted from the semiconductor light-emitting element to the outside of the semiconductor light-emitting device is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

204 (New). The semiconductor light-emitting device according to Claim 160, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a shielding body for shielding light directly emitted from the semiconductor light-emitting element to the outside of the semiconductor light-emitting device is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

205 (New). The semiconductor light-emitting device according to Claim 161, wherein

- the base substance is a substrate provided with metallic wiring;
- the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;
- a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;
- a shielding body for shielding light directly emitted from the semiconductor light-emitting element to the outside of the semiconductor light-emitting device is included;
- a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and
- a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

206 (New). The semiconductor light-emitting device according to Claim 157, wherein

- the base substance is a substrate provided with metallic wiring;
- the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;
- at least a light-emitting section of the semiconductor light-emitting element is disposed in a recessed portion in the substrate;
- a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;
- a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

207 (New). The semiconductor light-emitting device according to Claim 158, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

at least a light-emitting section of the semiconductor light-emitting element is disposed in a recessed portion in the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

208 (New). The semiconductor light-emitting device according to Claim 159, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

at least a light-emitting section of the semiconductor light-emitting element is disposed in a recessed portion in the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

209 (New). The semiconductor light-emitting device according to Claim 160, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

at least a light-emitting section of the semiconductor light-emitting element is disposed in a recessed portion in the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

210 (New). The semiconductor light-emitting device according to Claim 161, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

at least a light-emitting section of the semiconductor light-emitting element is disposed in a recessed portion in the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

211 (New). The semiconductor light-emitting device according to Claim 157, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the sealing resin that reflects light.

212 (New). The semiconductor light-emitting device according to Claim 158, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the sealing resin that reflects light.

213 (New). The semiconductor light-emitting device according to Claim 159, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the sealing resin that reflects light.

214 (New). The semiconductor light-emitting device according to Claim 160, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the sealing resin that reflects light.

215 (New). The semiconductor light-emitting device according to Claim 161, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the sealing resin that reflects light.

216 (New). A semiconductor light-emitting device constituted by mounting a semiconductor light-emitting element on a base substance, wherein

the semiconductor light-emitting element has outgoing light having emission wavelengths of 390 to 420 nm;

a first fluorescent substance, a second fluorescent substance and a third fluorescent substance are included;

the first fluorescent substance has red outgoing light having emission wavelengths with its main emission peak in a wavelength range of 600 to 670 nm;

the second fluorescent substance has green outgoing light having emission wavelengths with its main emission peak in a wavelength range of 500 to 540 nm;

the third fluorescent substance has blue outgoing light having emission wavelengths with its main emission peak in a wavelength range of 410 to 480 nm; and

the sum of colors of light emitted from the first, second and third fluorescent substances is a white color, wherein

the first fluorescent substance is composed of any one or more selected from a fluorescent substance group consisting of:

$M_2 O_2 S : Eu$ (M is any one or more elements selected from La, Gd and Y);

$0.5MgF_2 \cdot 3.5MgO \cdot GeO_2 : Mn$;

$Y_2 O_3 : Eu$,

$Y(P, V) O_4 : Eu$; and

$YVO_4 : Eu$;

the second fluorescent substance is composed of any one or more selected from a fluorescent substance group consisting of:

$\text{RMg}_2\text{Al}_{1.6}\text{O}_{2.7}$: Eu, Mn (R is any one or both elements selected from Sr and Ba);

$\text{RMgAl}_{1.0}\text{O}_{1.7}$: Eu, Mn (R is any one or both elements selected from Sr and Ba);

ZnS : Cu;

SrAl_2O_4 : Eu;

SrAl_2O_4 : Eu, Dy;

ZnO : Zn;

$\text{Zn}_2\text{Ge}_2\text{O}_4$: Mn;

Zn_2SiO_4 : Mn; and

$\text{Q}_3\text{MgSi}_2\text{O}_8$: Eu, Mn (Q is any one or more elements selected from Sr, Ba and Ca);
and

the third fluorescent substance is composed of any one or more selected from a fluorescent substance group consisting of:

$\text{A}_{1.0}(\text{PO}_4)_6\text{Cl}_2$: Eu (A is any one or more elements selected from Sr, Ca, Ba, Mg and Ce);

$\text{XMg}_2\text{Al}_{1.6}\text{O}_{2.7}$: E (X is any one or both elements selected from Sr and Ba);

$\text{XMgAl}_{1.0}\text{O}_{1.7}$: Eu (X is any one or both elements selected from Sr and Ba);

ZnS : Ag;

$\text{Sr}_{1.0}(\text{PO}_4)_6\text{Cl}_2 : \text{Eu};$

$\text{Ca}_{1.0}(\text{PO}_4)_6\text{F}_2 : \text{Sb};$

$\text{Z}_3\text{MgSi}_2\text{O}_8 : \text{Eu}$ (Z is any one or more elements selected from Sr, Ca and Ba);

$\text{SrMgSi}_2\text{O}_8 : \text{Eu};$

$\text{Sr}_2\text{P}_2\text{O}_7 : \text{Eu};$

$\text{CaAl}_2\text{O}_4 : \text{Eu, Nd.}$

217 (New). The semiconductor light-emitting device according to Claim 216, wherein, assuming the total amount as 100 weight %,

the first fluorescent substance is between 50 weight % and 70 weight % inclusive;

the second fluorescent substance is between 7 weight % and 20 weight % inclusive;
and

the third fluorescent substance is between 20 weight % and 30 weight % inclusive.

218 (New). The semiconductor light-emitting device according to Claim 217, wherein

the sealing resin contains the first, second and third fluorescent substances; and

the proportion of the total weight of the first, second and third fluorescent substances to the weight of the sealing resin is between 0.5 and 1 inclusive.

219 (New). A light-emitting display device comprising;

a light source using the semiconductor light-emitting device according to Claim 216;

a light guiding plate for guiding light from the light source; and
red, green and blue color filters for transmitting light from the light guiding plate and
dividing the light; the light-emitting display device, wherein

outgoing light from the semiconductor light-emitting device has a wavelength
distribution that matches spectral characteristics of the color filters.

220 (New). The light-emitting display device according to Claim 219, wherein at least one of the
following is adjusted so that the wavelength distribution of the outgoing light from the
semiconductor light-emitting device matches spectral characteristics of the color filters:

the emission wavelength of the semiconductor light-emitting element;

the emission wavelength of the first fluorescent substance;

the emission wavelength of the second fluorescent substance;

the emission wavelength of the third fluorescent substance;

the mixture proportions of the first, second and third fluorescent substances; and

the proportion of the total weight of the first, second and third fluorescent substances to the
weight of the sealing resin.

221 (New). The light-emitting display device according to Claim 219, wherein

the light-emitting display device is a liquid crystal display device.

222 (New). The light-emitting display device according to Claim 220, wherein

the light-emitting display device is a liquid crystal display device.